

## IPC Standards for Electronics PCB Assembly

NO.	IPC Standards	English	Chinese
1	IPC-T-50G	Terms and Definition for Interconnecting and Packaging Electronic Circuits	电子电路互连与封装的定义和术语
2	IPC-TM-650	Test Methods Manual	试验方法手册
3	IPC/EIA J-STD-001C	Requirements for Soldered Electrical & Electronic Assemblies	电气与电子组装件锡焊要求
4	IPC-HDBK-001	Handbook and Guide to Supplement J-STD-001—Includes Amendment 1	J-STD-001辅助手册及指南及修改说明1
5	IPC-A-610D	Acceptability of Electronic Assemblies	印制板组装件验收条件
6	IPC-HDBK-610	Handbook and Guide to IPC-A-610 (Includes IPC-A-610B to C Comparison)	IPC-610手册和指南(包括 IPC-A-610B和 C的对比)
7	IPC-EA-100-K	Electronic Assembly Reference Set	电子组装成套手册, 包括: IPC/EIA J-STD-001C, IPC-HDBK-001, IPC-A-610C。
8	IPC/WHMA-A-620	Requirements and Acceptance for Cable and Wire Harness Assemblies	电缆和引线贴装的要求和验收
9	IPC/EIA J-STD-012	Implementation of Flip Chip and Chip Scale Technology	倒装芯片及芯片级封装技术的应用
10	IPC-SM-784	Guidelines for Chip-on-Board Technology Implementation	芯片直装技术实施导则
11	IPC/EIA J-STD-026	Semiconductor Design Standard for Flip Chip Applications	倒装芯片用半导体设计标准
12	J-STD-027	Mechanical Outline Standard for Flip Chip and Chip Size Configurations	FC (倒装片) 和CSP(芯片级封装)的外形轮廓标准
13	IPC/EIA J-STD-028	Performance Standard for Construction of Flip Chip and Chip Scale Bumps	倒装芯片及芯片级凸块结构的性能标准
14	J-STD-013	Implementation of Ball Grid Array and Other High Density Technology	球栅阵列 (BGA)及其它高密度封装技术的应用
15	IPC-7095	Design and Assembly Process Implementation for BGAs	球栅阵列的设计与组装过程的实施
16	IPC/EIA J-STD-032	Performance Standard for Ball Grid Array Balls	BGA球形凸点的标准规范
17	IPC-MC-790	Guidelines for Multichip Module Technology Utilization	多芯片组件技术应用导则
18	IPC-M-108	Cleaning Guides and Handbook Manual	清洗导则和手册
19	IPC-5701	Users Guide for Cleanliness of Unpopulated Printed Boards	非密集型印制板清洁应用导则
20	IPC-TP-1113	Circuit Board Ionic Cleanliness Measurement: What Does It Tell Us?	电路板离子洁净度测量: 它告诉我们什么?
21	IPC-CH-65A	Guidelines for Cleaning of Printed Boards & Assemblies	印制板及组装件清洗导则
22	IPC-SC-60A	Post Solder Solvent Cleaning Handbook	锡焊后溶剂清洗手册
23	IPC-SA-61A	Post Solder Semi-aqueous Cleaning Handbook	锡焊后半水溶剂清洗手册
24	IPC-AC-62A	Aqueous Post Solder Cleaning Handbook	锡焊后水溶液清洗手册
25	IPC-TR-476A	Electrochemical Migration: Electrically Induced Failures in Printed Circuit Assemblies	电化学迁移: 印制电路组件的电气诱发故障
26	IPC-TR-582	Cleaning and Cleanliness Test Program for: Phase 3 --Low Solids, Fluxes and Pastes Processed in Ambient Air	IPC第3阶段非清洗助焊剂研究
27	IPC-TR-583	An In-Depth Look At Ionic Cleanliness Testing	深入离子洁净度测试
28	IPC-9201	Surface Insulation Resistance Handbook	表面绝缘电阻手册
29	IPC-TP-104-K	Cleaning & Cleanliness Test Program, Phase 3 Water Soluble Fluxes, Part 1 & Part 2	第3阶段水溶性助焊剂清洗, 第一和第二部分
30	IPC-M-109	Component Handling Manual	元件处理手册

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31	IPC/JEDEC J-STD-020C	Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices	非密封固态表面贴装器件湿度/再流焊敏感度分类
32	IPC/JEDEC J-STD-033A	Handling, Packing, Shipping and Use of Moisture/Reflow Sensitive Surface Mount Devices	对湿度、再流焊敏感表面贴装器件的处置、包装、发运和使用
33	IPC/JEDEC J-STD-035	Acoustic Microscopy for Non-Hermetic Encapsulated Electronic Components	非气密封装电子元件用声波显微镜
34	IPC-DRM-18G	Component Identification Desk Reference Manual	零件分类标识手册
35	IPC-DRM-smt-C	Surface Mount Solder Joint Evaluation Desk Reference Manual	接插件焊点评价手册
36	IPC-DRM-40E	Through-Hole Solder Joint Evaluation Desk Reference Manual	接插件焊点评价手册
37	IPC-DRM-56	Wire Preparation & Crimping Desk Reference Manual	导线和端子预成形参考手册
38	IPC-DRM-53	Introduction to Electronics Assembly Desk Reference Manual	电子组装基础介绍手册
39	IPC-M-103	Standards for Surface Mount Assemblies Manual	所有SMT标准合订本
40	IPC-M-104	Standards for Printed Board Assembly Manual	10种常用印制板组装标准合订本
41	IPC-TA-722	Technology Assessment of Soldering	锡焊技术精选手册
42	IPC-TA-723	Technology Assessment Handbook on Surface Mounting	表面安装技术精选手册
43	IPC-TA-724	Technology Assessment Series on Clean Rooms	清洁室技术精选系列
44	IPC-SM-780	Component Packaging and Interconnecting with Emphasis on Surface Mounting	以表面安装为主的元件封装及互连导则
45	IPC-SM-785	Guidelines Accelerated Reliability Testing of Surface Mount Attachments	表面安装焊件加速可靠性试验导则
46	IPC-9701	Performance Test Methods and Qualification Requirements for Surface Mount Solder Attachments	表面安装锡焊件性能试验方法与鉴定要求
47	IPC/JEDEC-9702	Monotonic Bend Characterization of Board-Level Interconnects	平板互连的单一弯曲特性
48	IPC-PD-335	Electronic Packaging Handbook	电子封装手册
49	IPC-7525	Stencil Design Guidelines	网版设计导则
50	IPC-QL 365A	Certification of Facilities That Inspect/Test Printed Boards, Components and Materials	印制板、元件和材料检验/试验企业的认证
51	IPC-9191	General Guidelines for Implementation of Statistical Process Control	统计过程控制导则
52	IPC-TR-581	IPC Phase III Controlled Atmosphere Soldering Study	IPC第3阶段受控气氛焊接研究
53	IPC-MI-660	Incoming Inspection of Raw Materials Manual	原材料接收检验手册
54	IPC/EIA J-STD-004A	Requirements for Soldering Fluxes-Includes Amendment 1	锡焊剂要求(包括修改单1)
55	IPC/EIA J-STD-005	Requirements for Soldering Pastes-Includes Amendment 1	焊膏技术要求(包括修改单1)
56	IPC-HDBK-005	Guide to Solder Paste Assessment	焊膏性能评价手册
57	IPC/EIA J-STD-006A	Requirements for Electronic Grade Solder Alloys and Fluxed and Non-Fluxed Solid Solders	电子设备用电子级锡焊合金、带焊剂及不带剂整体焊料技术要求
58	IPC-SM-817	General Requirements for Dielectric Surface Mounting Adhesives	表面安装用介电粘接剂通用要求
59	ELEC-SOLDER	Modern Solder Technology for Competitive Electronics Manufacturing	电子制造的最新焊接技术
60	IPC-WP-006	Round Robin Testing & Analysis: Lead-Free Alloys-Tin, Silver, & Copper	无铅焊料合金锡-银-铜的试验和分析求

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61	IPC-CA-821	General Requirements for Thermally Conductive Adhesives	导热胶粘剂通用要求
62	IPC-3406	Guidelines for Electrically Conductive Surface Mount Adhesives	表面贴装导电胶使用指南
63	IPC-3408	General Requirements for Anisotropically Conductive Adhesives Films	各向异性导电胶膜的一般要求
64	IPC-CC-830B	Qualification and Performance of Electrical Insulating Compound for Printed Wiring Assemblies	印制板组装电气绝缘性能和质量手册
65	IPC-HDBK-830	Guideline for Design, Selection and Application of Conformal Coatings	敷形涂层的设计, 选择和应用手册
66	IPC-SM-840C	Qualification and Performance of Permanent Solder Mask - Includes Amendment 1	永久性阻焊剂的鉴定及性能(包括修改单1)
67	IPC-HDBK-840	Guide to Solder Paste Assessment	焊膏性能评价手册
68	ELEC-MICRO	Handbook of Lead Free Solder Technology for Microelectronic Assemblies	微电子组装无铅焊接技术手册
69	IPC-TP-1114	The Layman's Guide to Qualifying a Process to J-STD-001	基于J-STD-001组装工艺雷氏选择法
70	IPC-AJ-820	Assembly & Joining Handbook	装联手册
71	IPC-7530	Guidelines for Temperature Profiling for Mass Soldering (Reflow & Wave) Processes	大规模焊接(回流焊与波峰焊)过程温度曲线指南
72	IPC-TP-1090	The Layman's Guide to Qualifying New Fluxes	新型助焊剂雷氏选择法
73	IPC-TP-1115	Selection and Implementation Strategy for a Low-Residue No-Clean Process	低残留不清洗工艺的选择和实施
74	IPC-S-816	SMT Process Guideline & Checklist	表面安装技术过程导则及检核表
75	IPC-TR-460A	Trouble-Shooting Checklist for Wave Soldering Printed Wiring Boards	印制板波峰焊故障排除检查表
76	IPC-CM-770E	Component Mounting Guidelines for Printed Boards	印制板元件安装导则
77	IPC-7912A	Calculation of DPMO & Manufacturing Indices for Printed Board Assemblies	印制板和电子组件每百万件缺陷数(DPMO)和制造指数的计算
78	IPC-9261	In-Process DPMO and Estimated Yield for PWAs	印制板组装过程中每百万件缺陷数(DPMO)及合格率估计
79	IPC-DPMO-202	IPC-7912/9261 End Item and In Process DPMO Set	IPC-7912A 和IPC-9261合订本
80	IPC-9500-K	Assembly Process Component Simulations, Guidelines & Classifications Package	组装过程中元件仿真, 规则分类
81	IPC-9501	PWB Assembly Process Simulation for Evaluation of Electronic Components	电子元件的印制板组装过程模拟评价
82	IPC-9502	PWB Assembly Soldering Process Guideline for Electronic Components	电子元件的印制板组装焊接过程导则
83	IPC-9503	Moisture Sensitivity Classification for Non-IC Components	非集成电路元件的湿度敏感度分级
84	IPC-9504	Assembly Process Simulation for Evaluation of Non-IC Components (Preconditioning Non-IC Components)	非集成电路元件的组装过程模拟评价(非集成电路元件预处理)
85	IPC-9850-K	Surface Mount Placement Equipment Characterization-KIT	表面贴装设备性能检测方法的描述(附Gerber格式CD盘)
86	IPC-9850-TM-KW, IPC-9850-TM-K	Test Materials Kit for Surface Mount Placement Equipment Stardization	表面贴装设备性能测试用的标准工具包
	• 4 IPC-9850	Placement Accuracy Verification Panels	电子元件放置精度验证板
	• 1 IPC-9850	CMM Measurement Verification Panels	CMM光学坐标测量系统验证板
	• 150 IPC-9850	QFP-100 Glass Components	QFP-100玻璃元件
	• 130 IPC-9850	QFP-208 Glass Components	QFP-208玻璃元件

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	<ul style="list-style-type: none"> <li>• 150 IPC-9850</li> </ul>	BGA-228 Glass Components	BGA-228玻璃元件
	<ul style="list-style-type: none"> <li>• NIST Traceable Measurement Certificate</li> </ul>	NIST Traceable Measurement Certificate	NIST可追溯的测量证书
	<ul style="list-style-type: none"> <li>• Custom Storage Case</li> </ul>	Custom Storage Case	定制收纳盒
87	IPC-7711/21A	Rework and Repair Guide	电子组装件的返工与返修
88	IPC/EIA J-STD-002B	Solderability Tests for Component Leads, Terminations, Lugs, Terminals and Wires	元件引线、端子、焊片、接线柱及导线可焊性试验
89	IPC/EIA J-STD-003A	Solderability Tests for Printed Boards	印制板可焊性试验
90	IPC-TR-461	Trouble-Shooting Checklist for Wave Soldering Printed Wiring Boards	印制板波峰焊故障排除检查表
91	IPC-TR-462	Solderability Evaluation of Printed Boards with Protective Coatings Over Long-term Storage	带保护性涂层印制板长期贮存的可焊性评价
92	IPC-TR-464	Accelerated Aging for Solderability Evaluations	可焊性加速老化评价(附修订)
93	IPC-TR-465-1	Round Robin Test on Steam Ager Temperature Control Stability	蒸汽老化器温度控制稳定性联合试验
94	IPC-TR-465-2	The Effect of Steam Aging Time and Temperature on Solderability Test Results	蒸汽老化时间与温度对可焊性试验结果的影响
95	IPC-TR-465-3	Evaluation of Steam Aging on Alternative Finishes, Phase IIA	替代涂覆层的蒸汽老化评价
96	IPC-TR-466	Technical Report: Wetting Balance Stard Weight Comparison Test	技术报告: 润湿天平称重标准对比测试
97	SMC-WP-001	Soldering Capability White Paper Report	可焊性工艺导论
98	SMC-WP-005	PCB Surface Finishes	印制电路板表面清洗